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(12) **United States Design Patent**
Chu

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(54) **THERMAL EFFICIENT HEAT SINK FOR ELECTRONIC DEVICES**

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(73) Assignee: **Datech Technology Co., Ltd.**, Taipei Hsien (TW)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/179**
(58) **Field of Search** D13/179; 165/80.3, 165/104.33, 121, 122, 146, 185; 257/697, 706, 707, 712, 718, 719, 720, 721, 722; 361/695, 697, 699, 702, 704, 709, 5, 14

(56) **References Cited**

U.S. PATENT DOCUMENTS

D453,744 S	*	2/2002	Lee et al.	D13/179
6,401,810 B1	*	6/2002	Kuo et al.	165/185
6,598,667 B1	*	7/2003	Kuo	165/80.3
6,637,502 B1	*	10/2003	North et al.	165/80.3
6,639,802 B1	*	10/2003	Dong et al.	361/709
6,651,734 B1	*	11/2003	Liu	165/80.3

* cited by examiner

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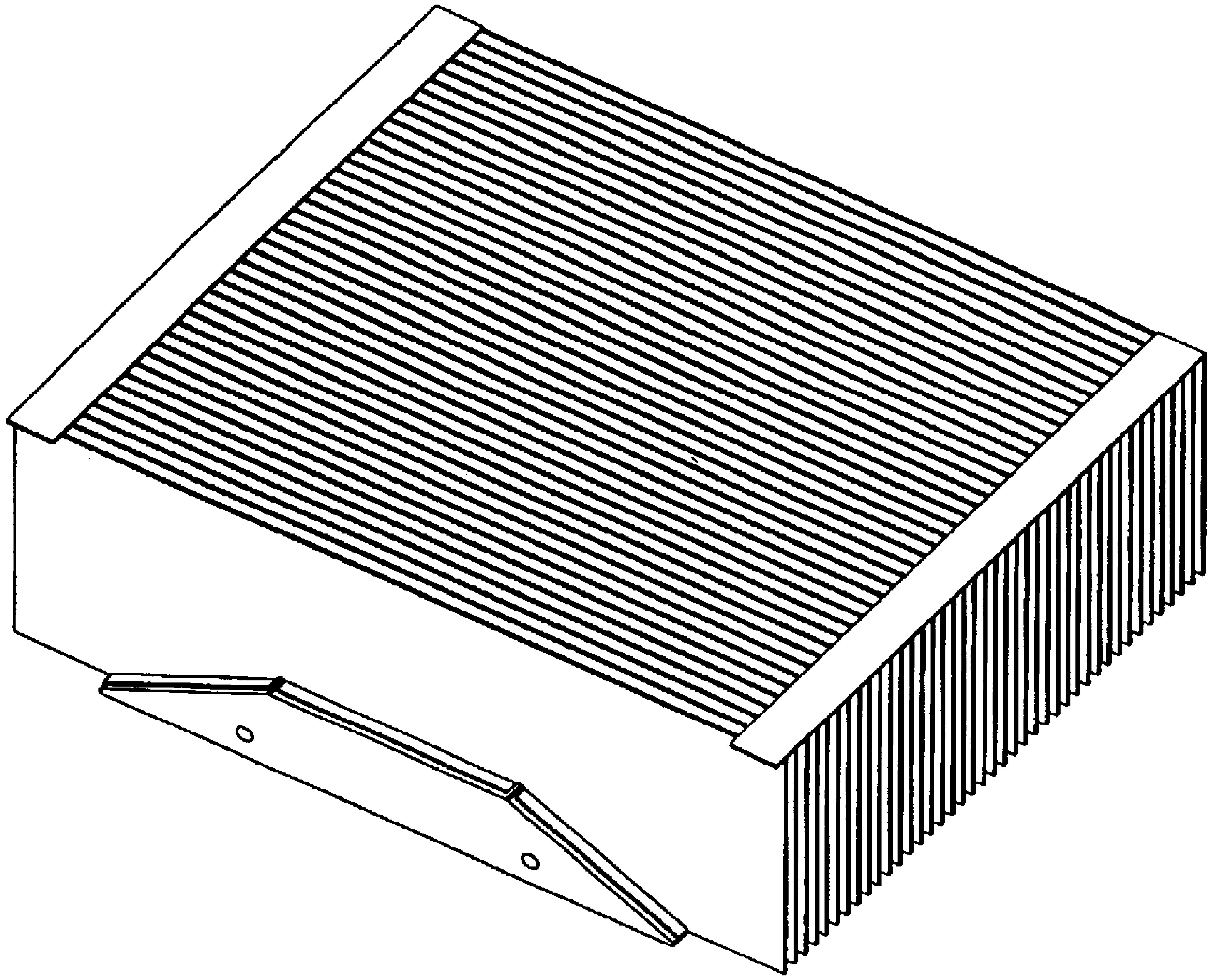
(57) **CLAIM**

The ornamental design for a thermal efficient heat sink for electronic devices, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a thermal efficient heat sink for electronic devices, in accordance with the present invention;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

1 Claim, 7 Drawing Sheets



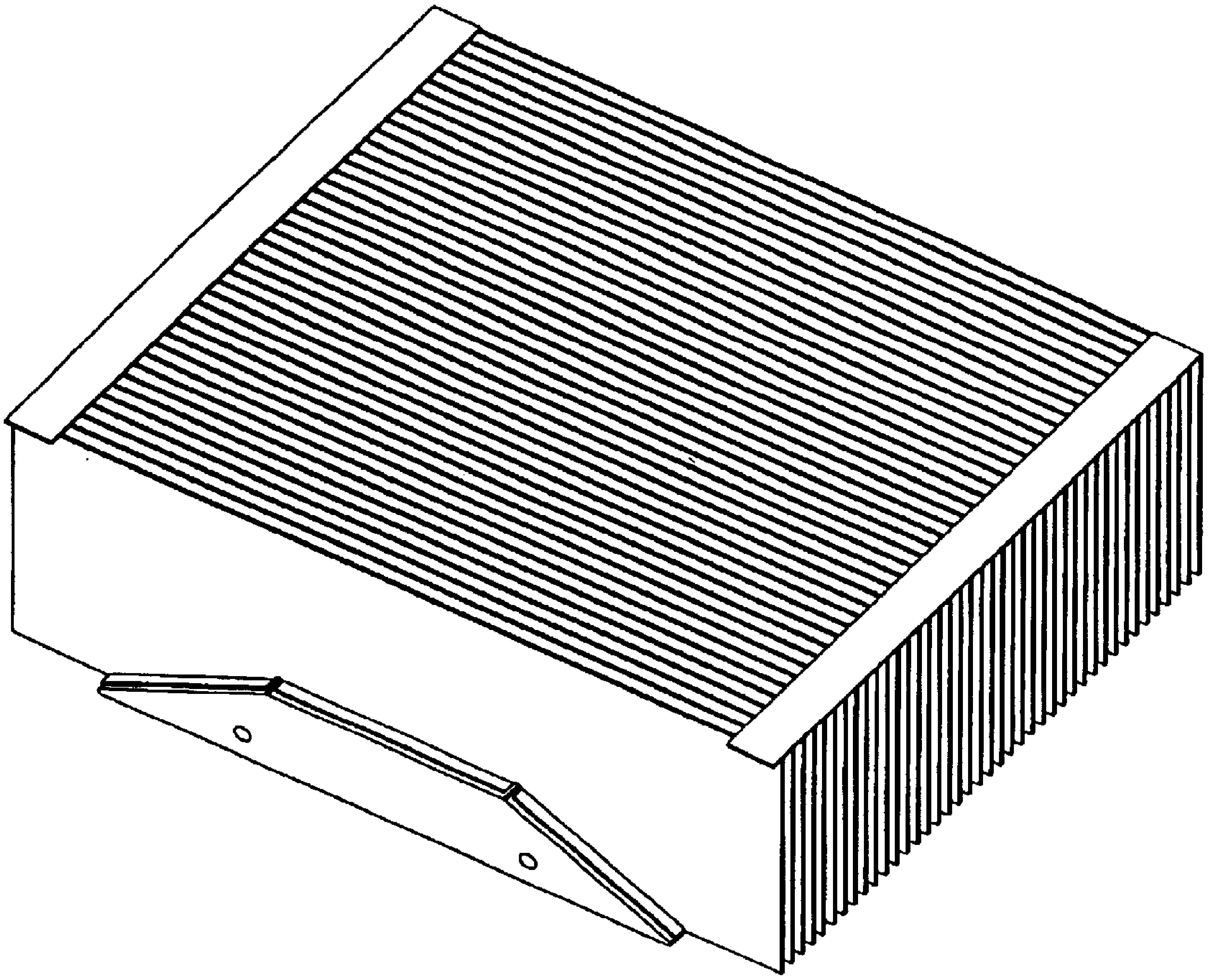


FIG. 1

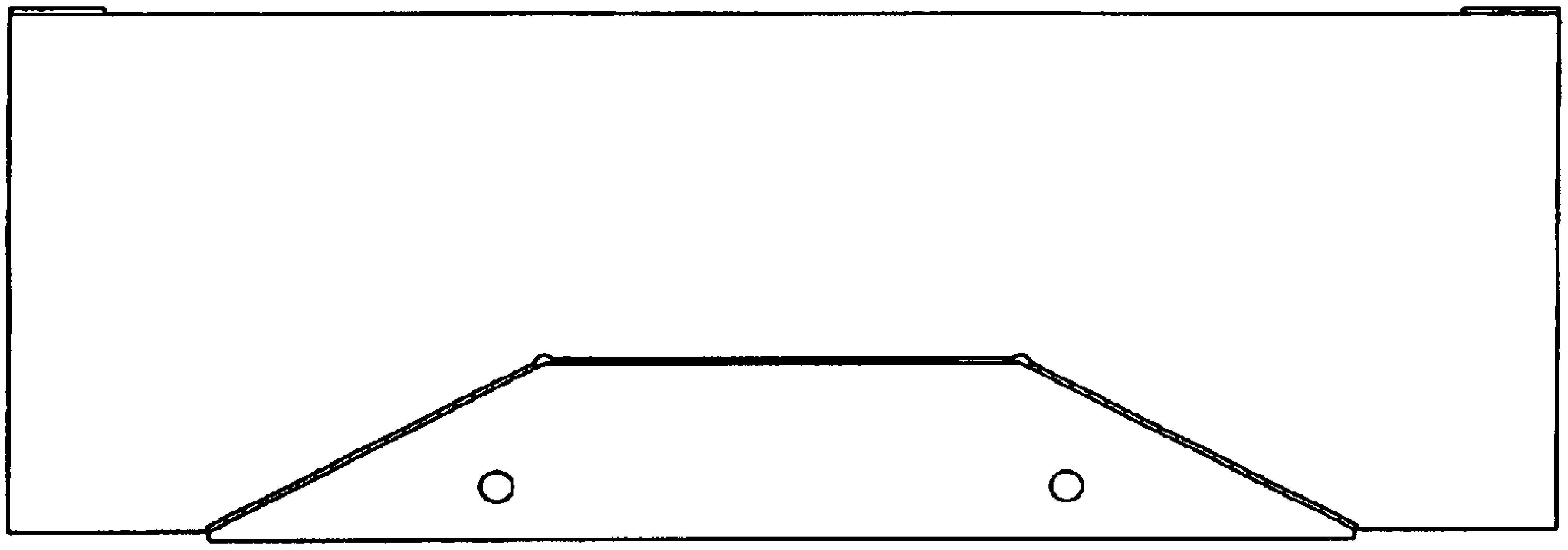


FIG. 2

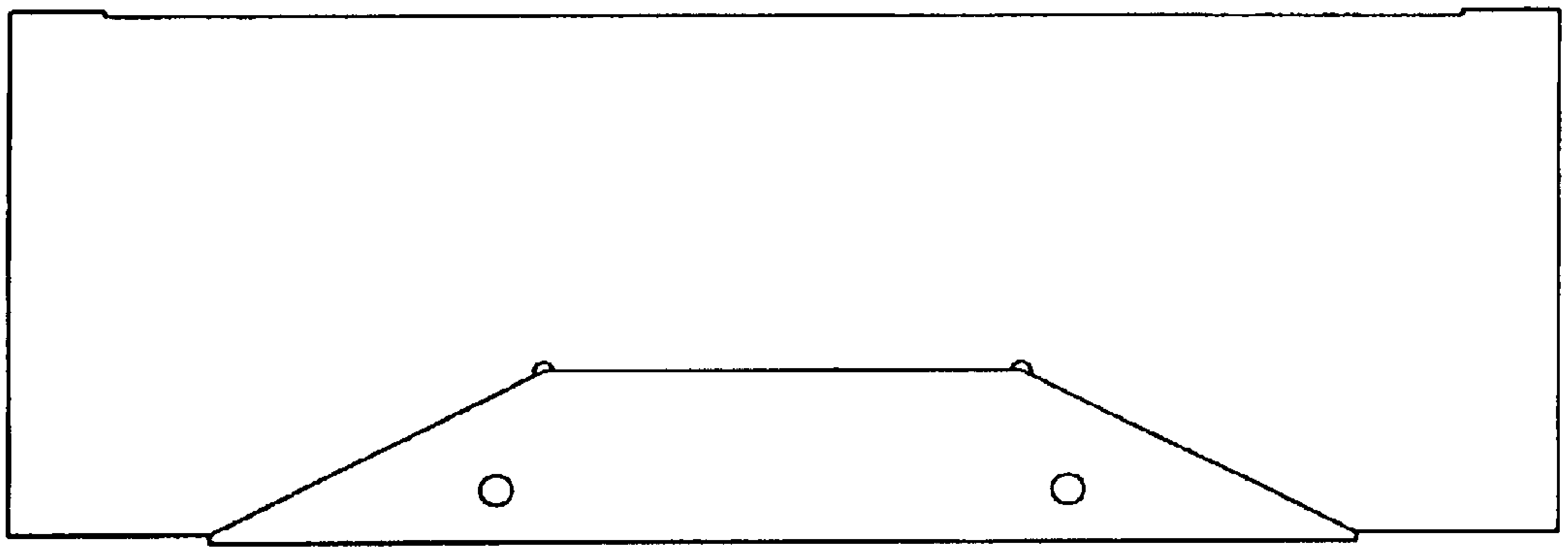


FIG. 3

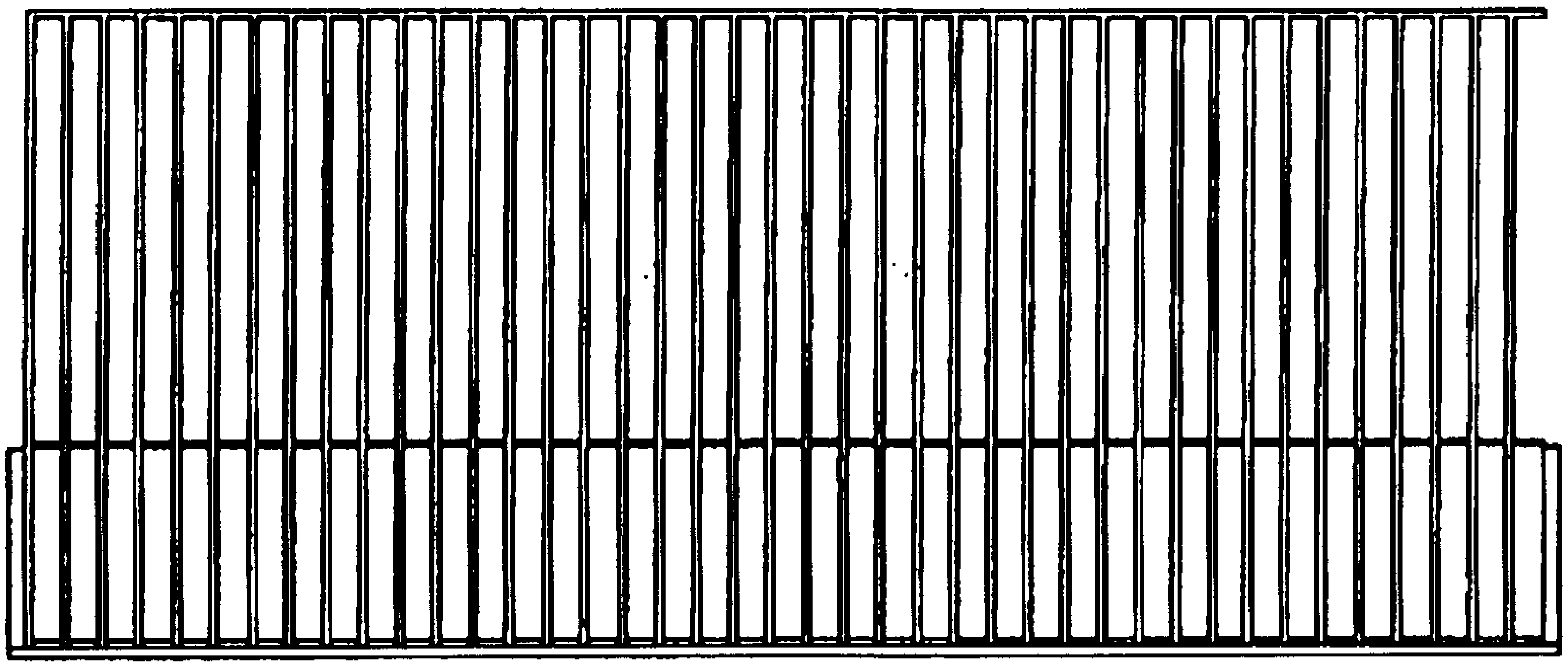


FIG. 4

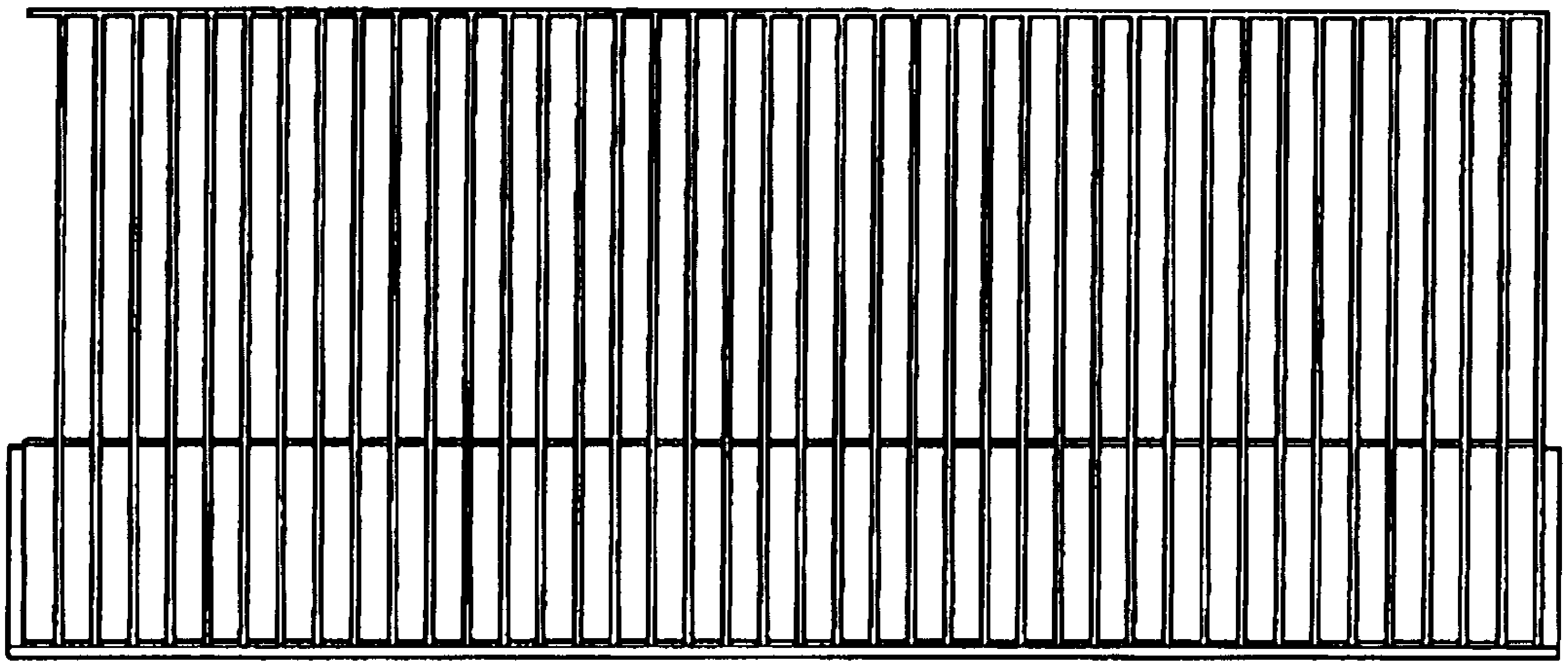


FIG. 5

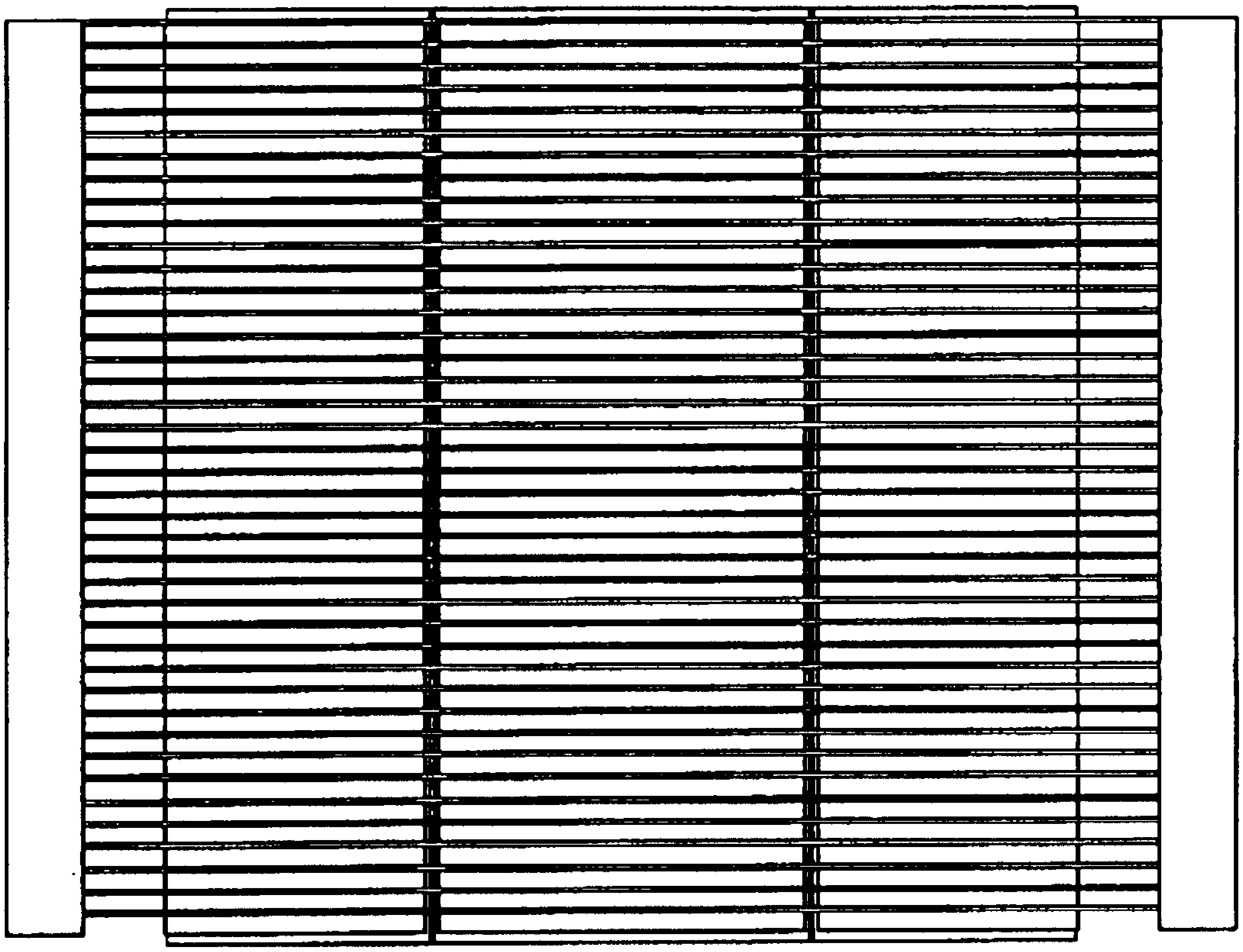


FIG. 6

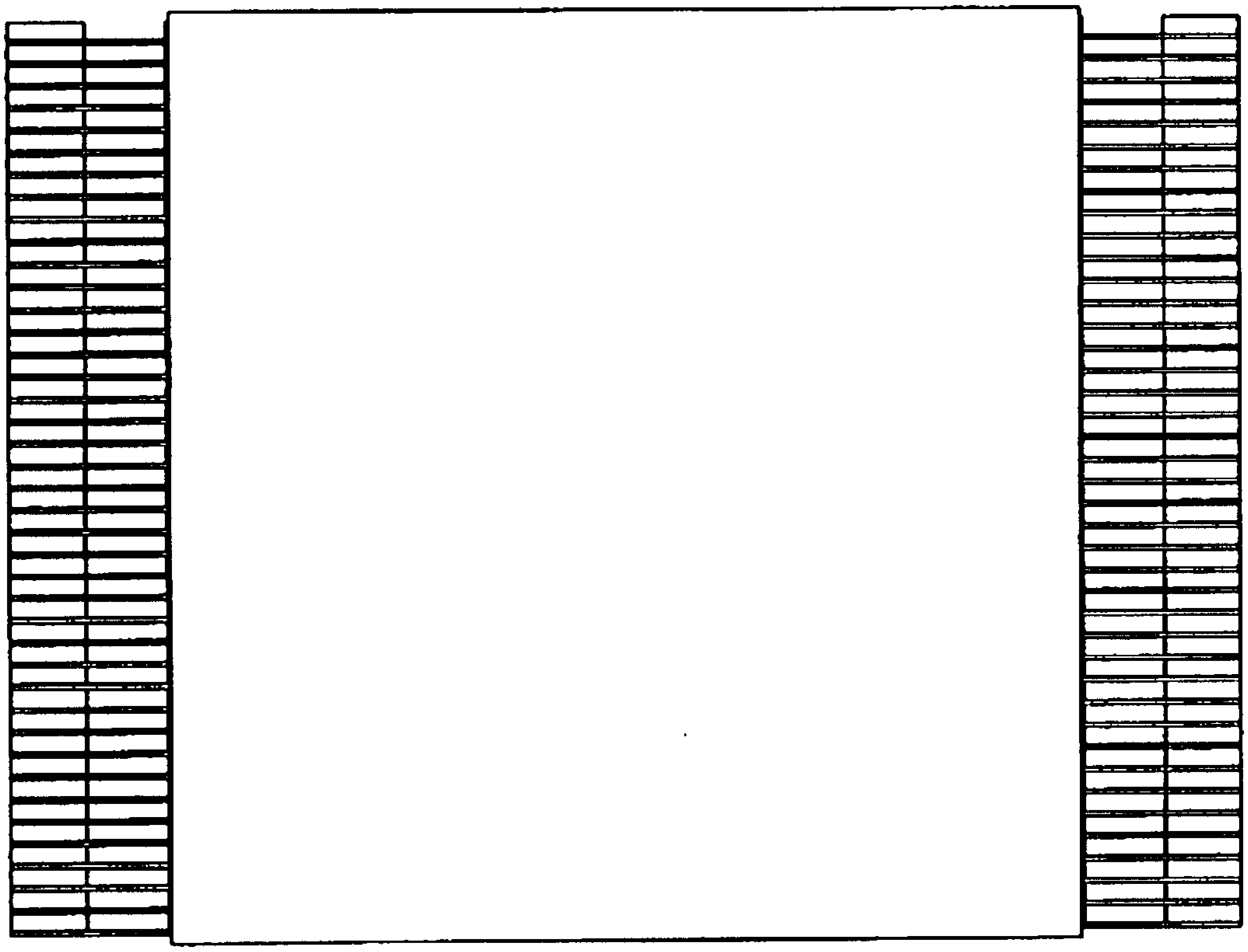


FIG. 7